

CSC THERMAL CONDUCTIVE PAD

TP-H1000 Series

Description & Applications

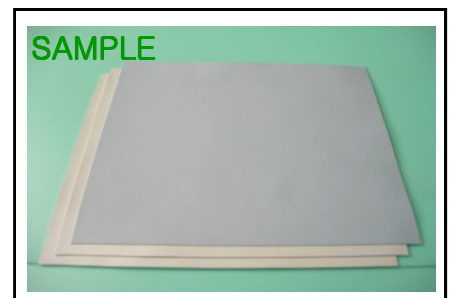
TP-H1000 is designed as a cost effective thermally conductive material. The soft and conformable properties allows the pad to apply to various heating devices. Primary use is to electrically isolate power sources from heat sinks.

- Power Electronics (SMPS, Converter)
- Automotive Electronics (ABS)
- Power Semiconductors



Main Features

- Thermal conductivity = 0.5 ~ 1.5 W/mK
- Enhanced mechanical properties
- Conformable hardness
- Electrically insulating



Specifications

ITEM	TP-H1000	METHOD
Mechanical		
Color*	Light Blue	Visual
Thickness (mm)	0.1 ~ 5.0	ASTM D374
Density (g/cc)	1.80	ASTM D792
Hardness (Shore A)	45	ASTM D2240
Tensile Strength (kgf/cm ²)	37.6	ASTM D412
Use Temp. (°C)	-60 ~ 200	-
Electrical		
Dielectric Breakdown Voltage (V)	> 6,000	ASTM D149
Volume Resistivity (Ω · cm)	10 ¹³	ASTM D257
Thermal		
Thermal Conductivity (W/mK)	1.0	ASTM C518-98 (Modified)
Flame Rating (UL94)	V-0	File No. E258204

※ Pad color can be adjustable upon request